

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. *(currently amended)* A cleaning substrate used in a process for cleaning and regenerating a mold having at least a mold cavity and a contaminated material layer formed on the mold cavity, the cleaning substrate including at least a first protrusion on the upper surface of the substrate which can substantially match with and be contained within the edges of the at least a mold cavity of the mold when the cleaning substrate is placed in the mold while the mold is contaminated after repeatedly packaging the semiconductor device.

2. (original) The cleaning substrate for cleaning and regenerating a mold of claim 1, wherein the profile of the protrusion is corresponding to the edges of the mold cavity.

3. (original) The cleaning substrate for cleaning and regenerating a mold of claim 1, wherein the substrate is made of paper.

4. *(currently amended)* [[A]] The cleaning substrate for cleaning and regenerating a mold of claim 1, wherein the mold is contaminated after repeatedly packaging the semiconductor device by making use of a thermosetting resin[[,]] the mold comprises at least an upper mold having at least a first recess, and a lower mold having at least a second recess, and the first recess and the second recess define [[a]] the mold cavity when the upper mold and the lower mold are tightly closed, wherein the cleaning substrate further comprises comprising at least a first protrusion on the upper surface of the substrate and at least a second protrusion on the lower surface of the

substrate, the first protrusion ~~substantially matching with and being~~ is contained within the edges of the first recess of the upper mold and the second protrusion ~~substantially matching with and being~~ is contained within the edges of the second recess of the lower mold ~~when the cleaning substrate is placed in the mold.~~

5. (original) The cleaning substrate for cleaning and regenerating a mold of claim 4, wherein the profile of the first protrusion is corresponding to the edges of the first recess of the upper mold and the profile of the second protrusion is corresponding to the edges of the second recess of the lower mold.

6-10. (canceled)

11. (new) A cleaning substrate for use in cleaning a semiconductor packaging mold having a plurality of mold cavities, said substrate comprising a strip of paper;

said strip having on an upper surface thereof a plurality of raised portions arranged to be spaced from each other, in a single row, longitudinally of said strip;

each of said raised portions being adapted to be completely received within one of the mold cavities of the mold.

12. (new) The substrate of claim 11, wherein each of said raised portions has a trapezoidal profile having slanted sides extending upward in a direction from the lower surface to the upper surface, and a generally flat top connecting said slanted sides.

13. (new) The substrate of claim 12, wherein the strip has a lower surface which is substantially flat throughout an entire area thereof.

14. (new) The substrate of claim 12, wherein the strip has on a lower surface thereof

another set of raised portions each corresponding to one of the raised portions on the upper surface and also having a trapezoidal profile with slanted sides extending downward in a direction from the upper surface to the lower surface, and a generally flat top connecting said slanted sides.

15. **(new)** In combination,

a semiconductor packaging mold having at least one mold cavity for packaging semiconductor packages; and

a cleaning substrate for use in cleaning said semiconductor packaging mold, said substrate having at least a first protrusion on the upper surface thereof, said first protrusion being sized and shaped to be completely received within said mold cavity.

16. **(new)** The combination of claim 15, wherein the first protrusion conforms in shape with said mold cavity.

17. **(new)** The combination of claim 16, wherein the substrate is made of paper.

18. **(new)** The combination of claim 17, wherein

the mold comprises at least an upper mold having at least a first recess, and a lower mold having at least a second recess, and the first recess and the second recess define said mold cavity when the upper mold and the lower mold are closed;

the cleaning substrate further comprises at least a second protrusion on the lower surface of the substrate, the first protrusion is completely contained within the first recess of the upper mold and the second protrusion is completely contained within the second recess of the lower mold when the cleaning substrate is placed in the mold and the mold is closed.

19. **(new)** The combination of claim 18, wherein the first and second protrusions conform in shape with said first and second recesses, respectively.

20. **(new)** The combination of claim 16, wherein the mold further comprises at least one pot, at least one runner, and at least one gate wherein the pot is connected to the mold cavity via the runner and the gate.

21. **(new)** The combination of claim 16, wherein the mold comprises a plurality of said mold cavities, said mold further comprising at least one pot, a plurality of runners, and a plurality of gates wherein the pot is connected to each of the mold cavities via one of the runners and one of the gates.

22. **(new)** The substrate of claim 13, wherein said raised portions are rectangular in plan view.